

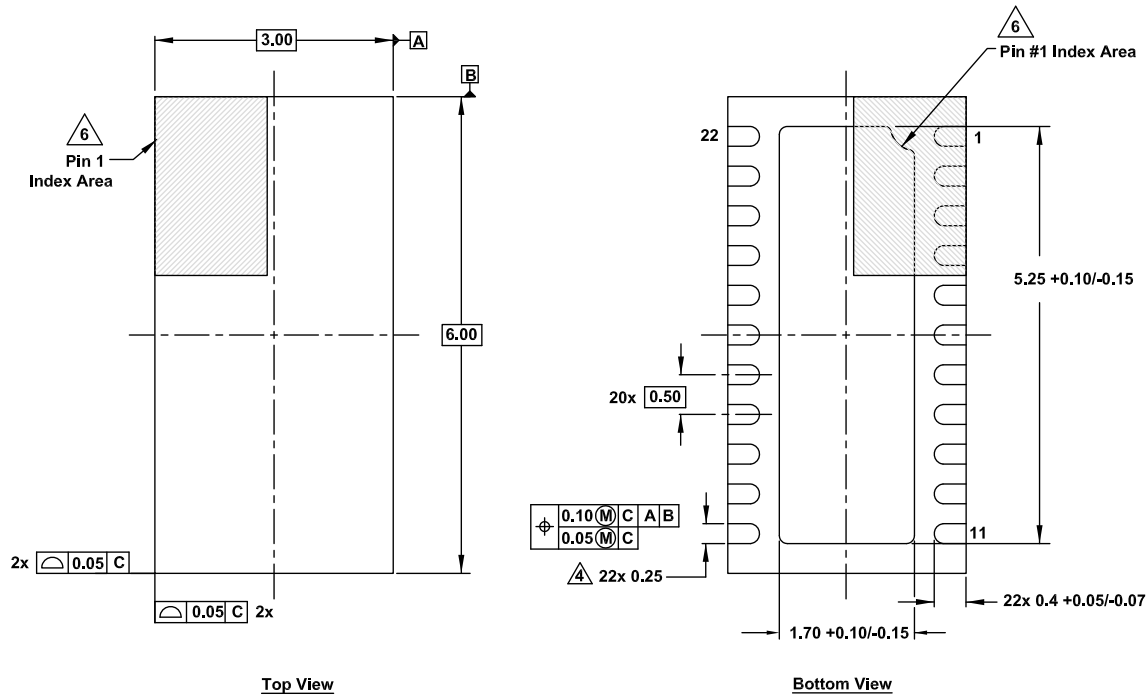
Plastic Packages for Integrated Circuits

Package Outline Drawing

L22.3x6

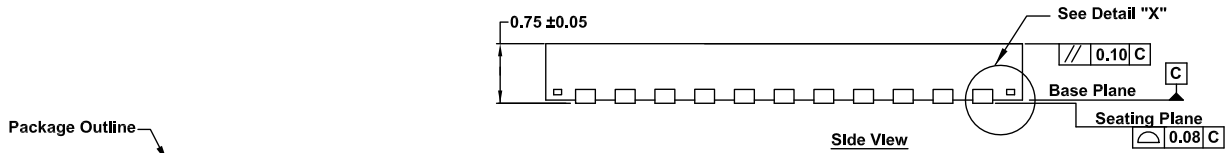
22 Lead Thin Dual Flat No-Lead Plastic Package (TDFN)

Rev 0, 3/18

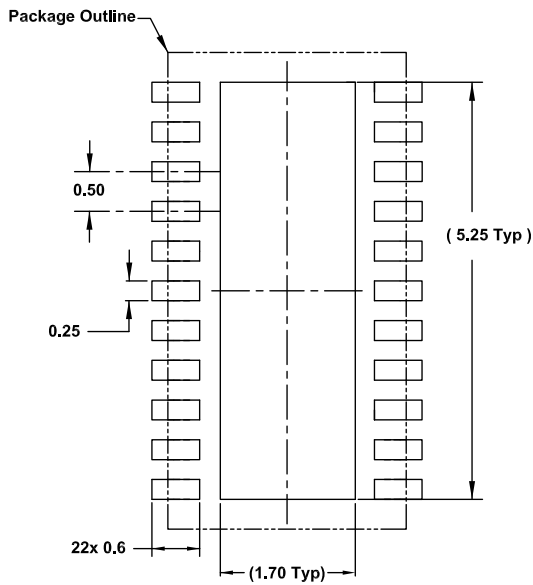


Top View

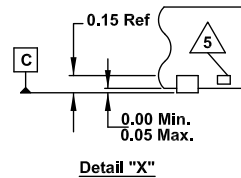
Bottom View



Side View



Typical Recommended Land Pattern



Detail "X"

Notes:

1. Dimensions are in millimeters.
Dimensions in () for reference only.
2. Dimensioning and tolerancing conform to AMSEY14.5m-1994.
3. Unless otherwise specified, tolerance : Decimal ± 0.05
4. Dimension applies to the metallized terminal and is measured between 0.20mm and 0.30mm from the terminal tip.
5. Tiebar shown (if present) is a non-functional feature.
6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.